



# 熱硬化型層間絶縁材料

## Zaristo Series

Thermal curable Build up Material for SAP

### Zaristo125 / Zaristo 517 X (Thermal curable Dry film for SAP)

#### 特長 Features

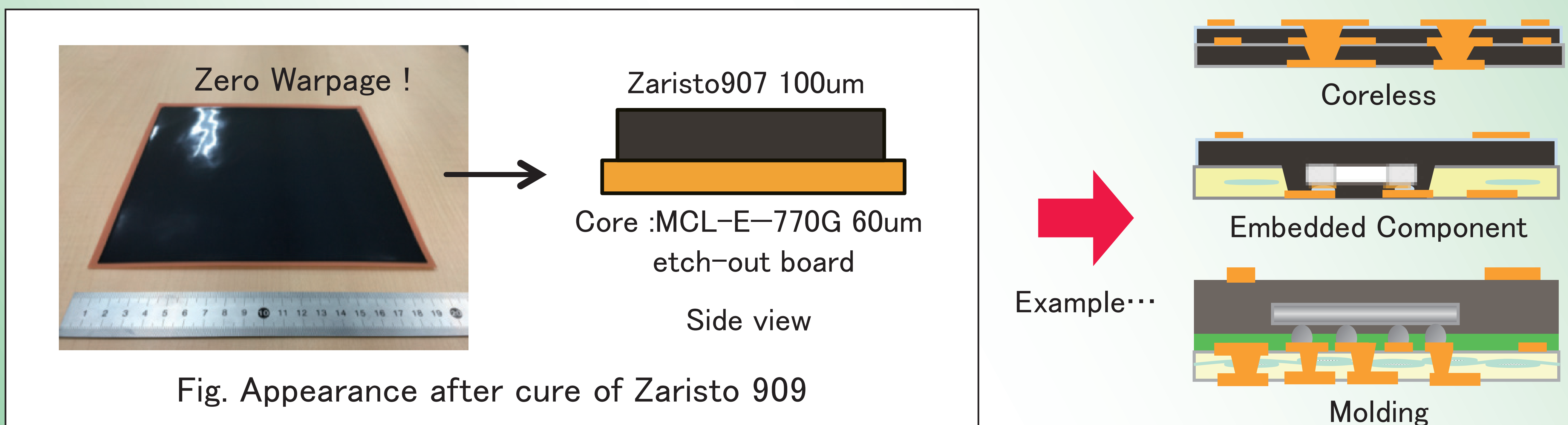
- SAP対応 Suitable for Conventional SAP
- 高BHAST耐性 Excellent LtL & L/S BHAST stability



### Zaristo 909 ( Thermal curable Dry film for MIS, ETS, Molding)

#### 特長 Features

- 超低反り Ultra Low Warpage after cure
- 低熱膨張&低弾性DF Low CTE & Low Modulus Dry film



Test Items	Unit	Zaristo125	Zaristo517X	Zaristo909
Target Application		SAP for FC-CSP,BGA	SAP for Server	MIS,ETS,Molding
Tg(TMA)	deg.C	165 - 175	165 - 175	>150
CTE α1	ppm	25 - 30	17	7 - 10
Young' Modulus	GPa	7 - 8	11 - 12	7.9 - 8.3
Dk(10GHz,SPDR)		3.4	3.4	3.5 - 3.6
Df(10GHz,SPDR)		0.015	0.004-0.005	0.006-0.009
Peel strength Ra after Desmear	N/cm um	>5.0 0.25~0.40	4.0 0.2~0.25	Available